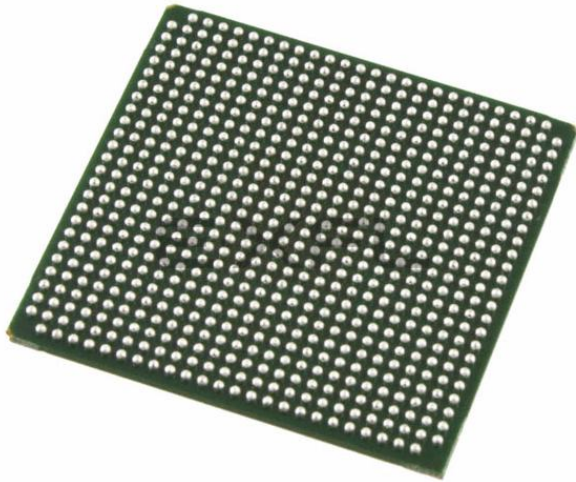




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

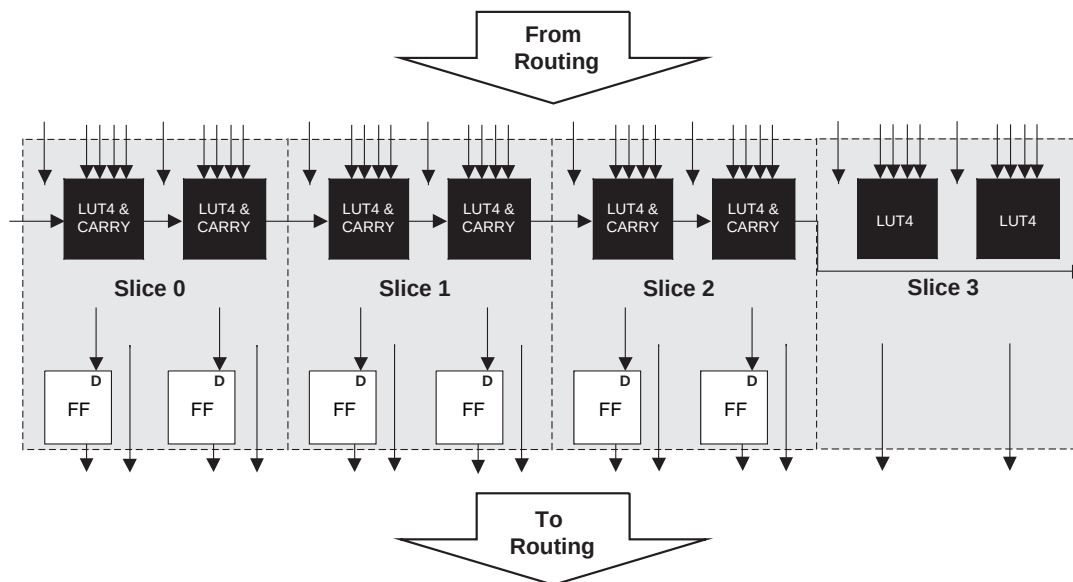
Product Status	Obsolete
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	396288
Number of I/O	500
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-50se-7f672c

PFU Blocks

The core of the LatticeECP2/M device consists of PFU blocks, which are provided in two forms, the PFU and PFF. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

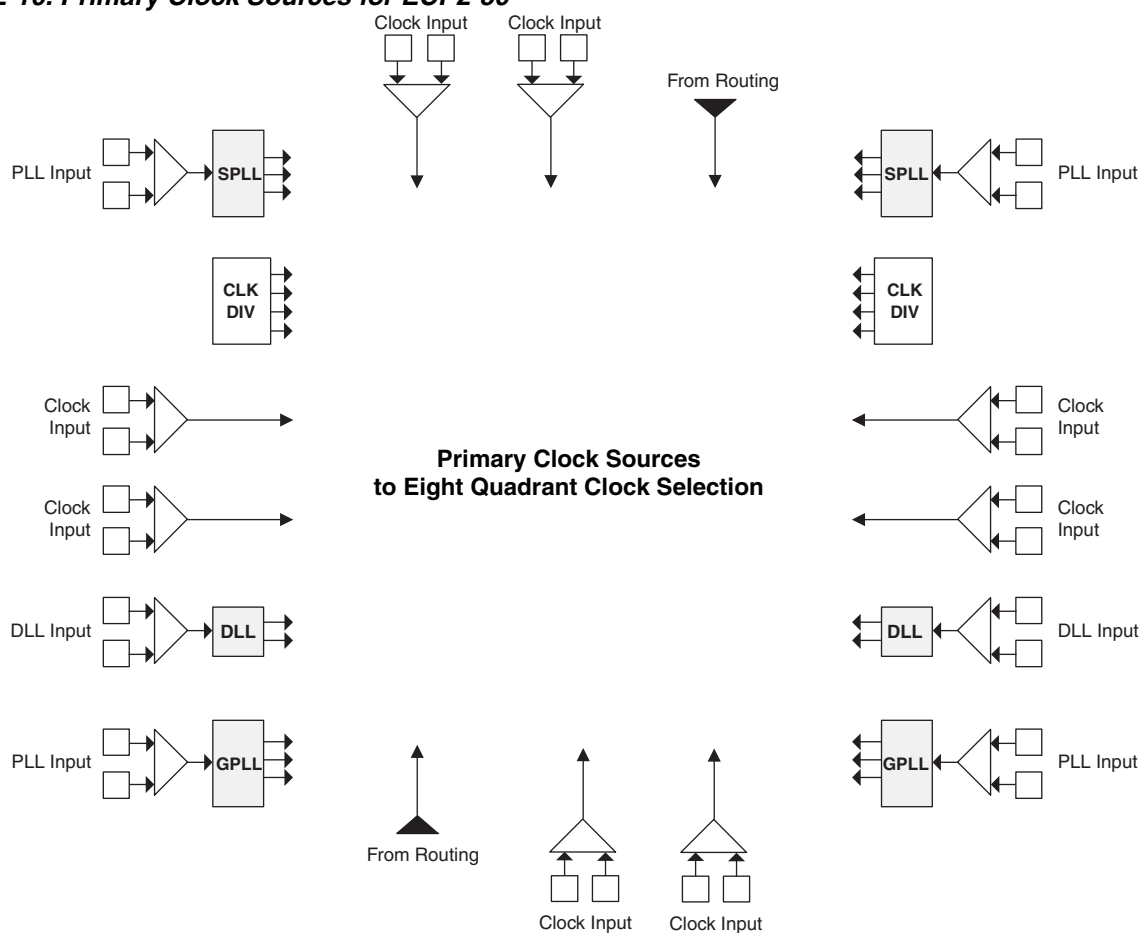
Slice 0 through Slice 2 contain two LUT4s feeding two registers, whereas Slice 3 contains two LUT4s only. For PFUs, Slice 0 and Slice 2 can also be configured as distributed memory, a capability not available in the PFF. Table 2-1 shows the capability of the slices in both PFF and PFU blocks along with the operation modes they enable. In addition, each PFU contains some logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Table 2-1. Resources and Modes Available per Slice

Slice	PFU BLock		PFF Block	
	Resources	Modes	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s	Logic, ROM	2 LUT4s	Logic, ROM

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 13 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

Figure 2-10. Primary Clock Sources for ECP2-50



Note: This diagram shows sources for the ECP2-50 device. Smaller LatticeECP2 devices have fewer SPLLs. All LatticeECP2M devices have six SPLLs.

DQSXFER

LatticeECP2/M devices provide a DQSXFER signal to the output buffer to assist it in data transfer to DDR memories that require DQS strobe be shifted 90°. This shifted DQS strobe is generated by the DQSDEL block. The DQSXFER signal runs the span of the data bus.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in groups referred to as banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysI/O Buffer Banks

LatticeECP2/M devices have nine sysI/O buffer banks: eight banks for user I/Os arranged two per side. The ninth sysI/O buffer bank (Bank 8) is located adjacent to Bank 3 and has dedicated/shared I/Os for configuration. When a shared pin is not used for configuration it is available as a user I/O. Each bank is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}). In addition, each bank, except Bank 8, has voltage references, V_{REF1} and V_{REF2} , which allow it to be completely independent from the others. Bank 8 shares two voltage references, V_{REF1} and V_{REF2} , with Bank 3. Figure 2-37 shows the nine banks and their associated supplies.

In LatticeECP2/M devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO} . LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold inputs independent of V_{CCIO} .

Each bank can support up to two separate V_{REF} voltages, V_{REF1} and V_{REF2} , that set the threshold for the referenced input buffers. Some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

for checking soft errors (SED) in SRAM. SED can be run on a programmed device when the user logic is not active. If a soft error occurs, during user mode (normal operation) the device can be programmed to either reload from a known good boot image or generate an error signal.

For further information about Soft Error Detect (SED) support, please see the list of additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP2/M devices require a single external, 10K ohm $\pm 1\%$ value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

On-Chip Oscillator

Every LatticeECP2/M device has an internal CMOS oscillator which is used to derive a Master Clock for configuration. The oscillator and the Master Clock run continuously and are available to user logic after configuration is completed. The software default value of the Master Clock is 2.5MHz. Table 2-16 lists all the available Master Configuration Clock frequencies for normal non-encrypted mode and encrypted mode. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a Master Clock frequency of 3.1MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the Master Clock frequency of 2.5MHz.

This internal CMOS oscillator is available to the user by routing it as an input clock to the clock tree. For further information about the use of this oscillator for configuration or user mode, please see the list of additional technical documentation at the end of this data sheet.

Table 2-16. Selectable Master Clock (CCLK) Frequencies During Configuration

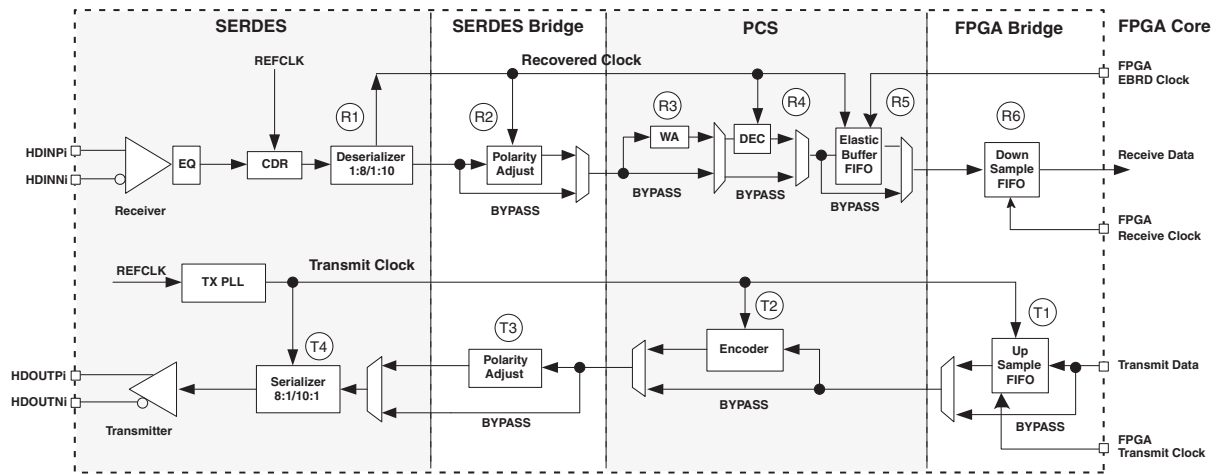
Non-Encrypted Mode CCLK (MHz)			Encrypted Mode CCLK (MHz)
2.5 ¹	13.0	45.0	2.5 ¹
4.3	15.0	55.0	5.4
5.4	20.0	60.0	10.0
6.9	26.0	—	—
8.1	30.0	—	—
9.2	34.0	—	—
10.0	41.0	130.0	—

1. Software default frequency.

Density Shifting

The LatticeECP2/M family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. Design migration between LatticeECP2 and LatticeECP2M families is not possible. For specific requirements relating to sysCONFIG pins of the ECP2M50, M70 and M100, see the Logic Signal Connections tables.

Figure 3-12. Transmitter and Receiver Block Diagram



SERDES External Reference Clock (LatticeECP2M Family Only)

The external reference clock selection and its interface are a critical part of system applications for this product. Table 3-14 specifies reference clock requirements, over the full range of operating conditions.

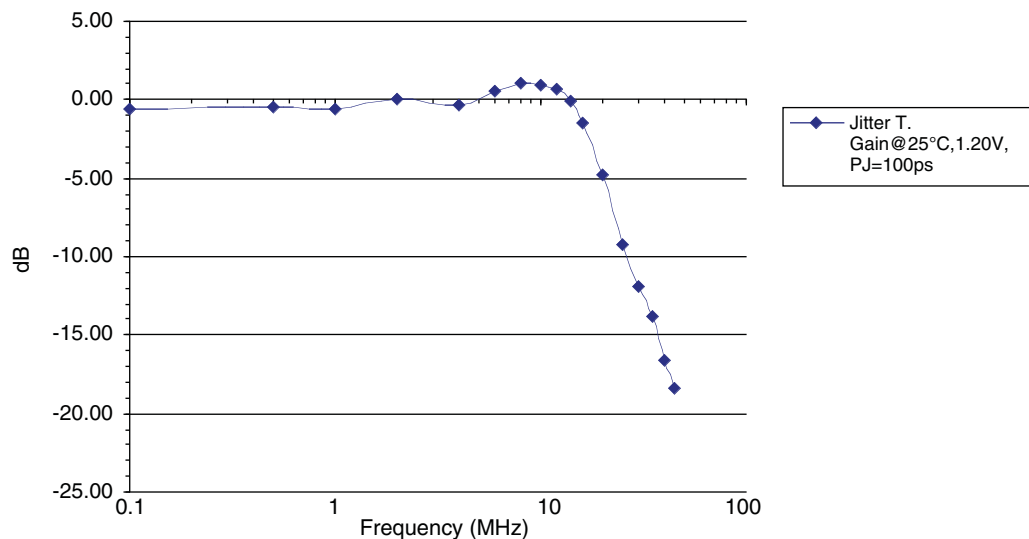
Table 3-14. External Reference Clock Specification (refclkp/refclkn)

Symbol	Description	Min.	Typ.	Max.	Units
F _{REF}	Frequency range	25	—	320	MHz
F _{REF-PPM}	Frequency tolerance	-300	—	300	ppm
V _{REF-IN-SE}	Input swing, single-ended clock ¹	100	—	1200	mV, p-p
V _{REF-IN}	Input levels	0	—	V _{CCP} + 0.8	V
V _{REF-CM-DC}	Input common mode range (DC coupled)	0.5	—	1.2	V
V _{REF-CM-AC}	Input common mode range (AC coupled) ²	0	—	1.5	V
D _{REF}	Duty cycle ³	40	—	60	%
T _{REF-R}	Rise time (20% to 80%)		500	1000	ps
T _{REF-F}	Fall time (80% to 20%)		500	1000	ps
Z _{REF-IN-TERM}	Input termination		50/2K		Ohms
C _{REF-IN-CAP}	Input capacitance ⁴	—	—	1.5	pF

1. The signal swing for a single-ended input clock must be as large as the p-p differential swing of a differential input clock to get the same gain at the input receiver. Lower swings for the clock may be possible, but will tend to increase jitter.
2. When AC coupled, the input common mode range is determined by:

$$(\text{Min input level}) + (\text{Peak-to-peak input swing})/2 \leq (\text{Input common mode voltage}) \leq (\text{Max input level}) - (\text{Peak-to-peak input swing})/2$$
3. Measured at 50% amplitude.
4. Input capacitance of 1.5pF is total capacitance, including both device and package.

Figure 3-13. Jitter Transfer



Note: This graph is for a nominal device.

SERDES Power-Down/Power-Up Specification

Table 3-15. Power-Down and Power-Up Specification

Symbol	Description	Max.	Units
t _{PWRDN}	Power-down time after all power down register bits set to '0'	10	μs
t _{PWRUP}	Power-up time after all power down register bits set to '1'	100	μs

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP

LFE2-6E/SE					LFE2-12E/12SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
1	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*	
2	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*	
3	PL4A	7		T (LVDS)*	PL4A	7		T (LVDS)*	
4	PL4B	7		C (LVDS)*	PL4B	7		C (LVDS)*	
5	PL6A	7	LDQ10	T (LVDS)*	PL6A	7	LDQ10	T (LVDS)*	
6	VCCAUX	-			VCCAUX	-			
7	PL6B	7	LDQ10	C (LVDS)*	PL6B	7	LDQ10	C (LVDS)*	
8	PL8A	7	LDQ10	T (LVDS)*	PL8A	7	LDQ10	T (LVDS)*	
9	VCCIO7	7			VCCIO7	7			
10	PL8B	7	LDQ10	C (LVDS)*	PL8B	7	LDQ10	C (LVDS)*	
11	GND	-			GND	-			
12	PL12A	7	LDQ10	T (LVDS)*	PL12A	7	LDQ10	T (LVDS)*	
13	PL12B	7	LDQ10	C (LVDS)*	PL12B	7	LDQ10	C (LVDS)*	
14	PL13A	7	PCLKT7_0/LDQ10	T	PL13A	7	PCLKT7_0/LDQ10	T	
15	PL13B	7	PCLKC7_0/LDQ10	C	PL13B	7	PCLKC7_0/LDQ10	C	
16	VCC	-			VCC	-			
17	PL15A	6	PCLKT6_0	T (LVDS)*	PL15A	6	PCLKT6_0	T (LVDS)*	
18	PL15B	6	PCLKC6_0	C (LVDS)*	PL15B	6	PCLKC6_0	C (LVDS)*	
19	PL16A	6	VREF2_6	T	PL16A	6	VREF2_6	T	
20	PL16B	6	VREF1_6	C	PL16B	6	VREF1_6	C	
21	GND	-			GND	-			
22	VCC	-			VCC	-			
23	PL18A	6	LLM0_GDLLT_FB_A	T	PL18A	6	LLM0_GDLLT_FB_A	T	
24	PL18B	6	LLM0_GDLLC_FB_A	C	PL18B	6	LLM0_GDLLC_FB_A	C	
25	LLM0_PLLCAP	6			LLM0_PLLCAP	6			
26	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	
27	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	
28	PL22A	6			PL22A	6			
29	VCC	-			VCC	-			
30	GND	-			GND	-			
31	VCCIO6	6			VCCIO6	6			
32	TCK	-			TCK	-			
33	TDI	-			TDI	-			
34	TDO	-			TDO	-			
35	VCCJ	-			VCCJ	-			
36	TMS	-			TMS	-			
37	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T	
38	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C	
39	VCCAUX	-			VCCAUX	-			
40	PB4A	5	BDQ6	T	PB6A	5	BDQS6	T	
41	PB4B	5	BDQ6	C	PB6B	5	BDQ6	C	
42	VCCIO5	5			VCCIO5	5			
43	PB6A	5	BDQS6	T	PB12A	5	BDQ15	T	
44	PB6B	5	BDQ6	C	PB12B	5	BDQ15	C	
45	NC	5			PB16A	5	BDQ15	T	

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB38B	5	BDQ42	C	PB47B	5	BDQ51	C
AE10	PB39A	5	BDQ42	T	PB48A	5	BDQ51	T
AF10	PB39B	5	BDQ42	C	PB48B	5	BDQ51	C
W14	PB40A	5	BDQ42	T	PB49A	5	BDQ51	T
AB13	PB40B	5	BDQ42	C	PB49B	5	BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y14	PB41A	5	BDQ42	T	PB50A	5	BDQ51	T
AB14	PB41B	5	BDQ42	C	PB50B	5	BDQ51	C
GND	GNDIO5	-			GNDIO5	-		
AE11	PB42A	5	BDQS42	T	PB51A	5	BDQS51	T
AF11	PB42B	5	BDQ42	C	PB51B	5	BDQ51	C
AD14	PB43A	5	BDQ42	T	PB52A	5	BDQ51	T
AA15	PB43B	5	BDQ42	C	PB52B	5	BDQ51	C
AE12	PB44A	5	PCLKT5_0/BDQ42	T	PB53A	5	PCLKT5_0/BDQ51	T
AF12	PB44B	5	PCLKC5_0/BDQ42	C	PB53B	5	PCLKC5_0/BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
GND	GNDIO5	-			GNDIO5	-		
AD15	PB49A	4	PCLKT4_0/BDQ51	T	PB58A	4	PCLKT4_0/BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
AC15	PB49B	4	PCLKC4_0/BDQ51	C	PB58B	4	PCLKC4_0/BDQ60	C
AE13	PB50A	4	BDQ51	T	PB59A	4	BDQ60	T
AF13	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
AB17	PB51A	4	BDQS51	T	PB60A	4	BDQS60	T
GND	GNDIO4	-			GNDIO4	-		
Y15	PB51B	4	BDQ51	C	PB60B	4	BDQ60	C
AE14	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
AF14	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
AA16	PB53A	4	BDQ51	T	PB62A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
W15	PB53B	4	BDQ51	C	PB62B	4	BDQ60	C
AC17	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
AB16	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
AE15	PB55A	4	BDQ51	T	PB64A	4	BDQ60	T
GND	GNDIO4	-			GNDIO4	-		
AF15	PB55B	4	BDQ51	C	PB64B	4	BDQ60	C
AE16	PB56A	4	BDQ60	T	PB65A	4	BDQ69	T
AF16	PB56B	4	BDQ60	C	PB65B	4	BDQ69	C
Y16	PB57A	4	BDQ60	T	PB66A	4	BDQ69	T
AB18	PB57B	4	BDQ60	C	PB66B	4	BDQ69	C
AD17	PB58A	4	BDQ60	T	PB67A	4	BDQ69	T
AD18	PB58B	4	BDQ60	C	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
AC18	PB59A	4	BDQ60	T	PB68A	4	BDQ69	T
AD19	PB59B	4	BDQ60	C	PB68B	4	BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AC19	PB60A	4	BDQS60	T	PB69A	4	BDQS69	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
Y21	PB82A	4	VREF2_4/BDQ78	T	PB100A	4	VREF2_4/BDQ96	T	
AB23	PB82B	4	VREF1_4/BDQ78	C	PB100B	4	VREF1_4/BDQ96	C	
GND	GNDIO4	-			GNDIO4	-			
AD24	CFG2	8			CFG2	8			
W20	CFG1	8			CFG1	8			
AC24	CFG0	8			CFG0	8			
V19	PROGRAMN	8			PROGRAMN	8			
AA22	CCLK	8			CCLK	8			
AB24	INITN	8			INITN	8			
AD25	DONE	8			DONE	8			
GND	GNDIO8	-			GNDIO8	-			
W21	PR77B	8	WRITEN	C	PR90B	8	WRITEN	C	
Y22	PR77A	8	CS1N	T	PR90A	8	CS1N	T	
AC25	PR76B	8	CSN	C	PR89B	8	CSN	C	
AB25	PR76A	8	D0/SPIFASTN	T	PR89A	8	D0/SPIFASTN	T	
VCCIO	VCCIO8	8			VCCIO8	8			
AD26	PR75B	8	D1	C	PR88B	8	D1	C	
AC26	PR75A	8	D2	T	PR88A	8	D2	T	
Y23	PR74B	8	D3	C	PR87B	8	D3	C	
GND	GNDIO8	-			GNDIO8	-			
W22	PR74A	8	D4	T	PR87A	8	D4	T	
AA25	PR73B	8	D5	C	PR86B	8	D5	C	
AB26	PR73A	8	D6	T	PR86A	8	D6	T	
W23	PR72B	8	D7/SPID0	C	PR85B	8	D7/SPID0	C	
VCCIO	VCCIO8	8			VCCIO8	8			
V22	PR72A	8	DI/CSSPI0N	T	PR85A	8	DI/CSSPI0N	T	
Y24	PR71B	8	DOUT/CSON	C	PR84B	8	DOUT/CSON	C	
Y25	PR71A	8	BUSY/SISPI	T	PR84A	8	BUSY/SISPI	T	
W24	PR70B	3	RDQ67	C	PR83B	3	RDQ80	C	
GND	GNDIO3	-			GNDIO3	-			
V23	PR70A	3	RDQ67	T	PR83A	3	RDQ80	T	
AA26	PR69B	3	RDQ67	C (LVDS)*	PR82B	3	RDQ80	C (LVDS)*	
Y26	PR69A	3	RDQ67	T (LVDS)*	PR82A	3	RDQ80	T (LVDS)*	
U21	PR68B	3	RDQ67	C	PR81B	3	RDQ80	C	
VCCIO	VCCIO3	3			VCCIO3	3			
U19	PR68A	3	RDQ67	T	PR81A	3	RDQ80	T	
W25	PR67B	3	RDQ67	C (LVDS)*	PR80B	3	RDQ80	C (LVDS)*	
W26	PR67A	3	RDQS67	T (LVDS)*	PR80A	3	RDQS80	T (LVDS)*	
GND	GNDIO3	-			GNDIO3	-			
V24	PR66B	3	RDQ67	C	PR79B	3	RDQ80	C	
V25	PR66A	3	RDQ67	T	PR79A	3	RDQ80	T	
V26	PR65B	3	RDQ67	C (LVDS)*	PR78B	3	RDQ80	C (LVDS)*	
U26	PR65A	3	RDQ67	T (LVDS)*	PR78A	3	RDQ80	T (LVDS)*	
VCCIO	VCCIO3	3			VCCIO3	3			
U22	PR64B	3	RLM0_GPLL_C_FB_A/RDQ67	C	PR77B	3	RLM0_GPLL_C_FB_A/RDQ80	C	
U23	PR64A	3	RLM0_GPLL_T_FB_A/RDQ67	T	PR77A	3	RLM0_GPLL_T_FB_A/RDQ80	T	

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO2	-			GNDIO2	-		
L21	PR43B	2	RDQ41	C (LVDS)*	PR56B	2	RDQ54	C (LVDS)*
K22	PR43A	2	RDQ41	T (LVDS)*	PR56A	2	RDQ54	T (LVDS)*
M24	PR42B	2	RDQ41	C	PR55B	2	RDQ54	C
N23	PR42A	2	RDQ41	T	PR55A	2	RDQ54	T
VCCIO	VCCIO2	2			VCCIO2	2		
K26	PR41B	2	RDQ41	C (LVDS)*	PR54B	2	RDQ54	C (LVDS)*
K25	PR41A	2	RDQS41	T (LVDS)*	PR54A	2	RDQS54	T (LVDS)*
M20	PR40B	2	RDQ41	C	PR53B	2	RDQ54	C
GND	GNDIO2	-			GNDIO2	-		
M19	PR40A	2	RDQ41	T	PR53A	2	RDQ54	T
L22	PR39B	2	RDQ41	C (LVDS)*	PR52B	2	RDQ54	C (LVDS)*
M22	PR39A	2	RDQ41	T (LVDS)*	PR52A	2	RDQ54	T (LVDS)*
K21	PR38B	2	RDQ41	C	PR51B	2	RDQ54	C
VCCIO	VCCIO2	2			VCCIO2	2		
M21	PR38A	2	RDQ41	T	PR51A	2	RDQ54	T
K24	PR37B	2	RDQ41	C (LVDS)*	PR50B	2	RDQ54	C (LVDS)*
J24	PR37A	2	RDQ41	T (LVDS)*	PR50A	2	RDQ54	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
VCCIO	VCCIO2	2			VCCIO2	2		
L20	VCCPLL	2			NC	-		
GND	GNDIO2	-			GNDIO2	-		
J26	PR26B	2	RUM0_SPLLC_FB_A/RDQ24	C	PR39B	2	RUM0_SPLLC_FB_A/RDQ37	C
J25	PR26A	2	RUM0_SPLLT_FB_A/RDQ24	T	PR39A	2	RUM0_SPLLT_FB_A/RDQ37	T
J23	PR25B	2	RUM0_SPLLC_IN_A/RDQ24	C	PR38B	2	RUM0_SPLLC_IN_A/RDQ37	C
K23	PR25A	2	RUM0_SPLLT_IN_A/RDQ24	T	PR38A	2	RUM0_SPLLT_IN_A/RDQ37	T
VCCIO	VCCIO2	2			VCCIO2	2		
H26	PR24B	2	RDQ24	C (LVDS)*	PR37B	2	RDQ37	C (LVDS)*
H25	PR24A	2	RDQS24***	T (LVDS)*	PR37A	2	RDQS37***	T (LVDS)*
H24	PR23B	2	RDQ24	C	PR36B	2	RDQ37	C
GND	GNDIO2	-			GNDIO2	-		
H23	PR23A	2	RDQ24	T	PR36A	2	RDQ37	T
VCCIO	VCCIO2	2			VCCIO2	2		
G26	PR19B	2	RDQ16	C	PR32B	2	RDQ29	C
GND	GNDIO2	-			GNDIO2	-		
G25	PR19A	2	RDQ16	T	PR32A	2	RDQ29	T
F26	PR18B	2	RDQ16	C (LVDS)*	PR31B	2	RDQ29	C (LVDS)*
F25	PR18A	2	RDQ16	T (LVDS)*	PR31A	2	RDQ29	T (LVDS)*
K20	PR17B	2	RDQ16	C	PR30B	2	RDQ29	C
VCCIO	VCCIO2	2			VCCIO2	2		
L19	PR17A	2	RDQ16	T	PR30A	2	RDQ29	T
E26	PR16B	2	RDQ16	C (LVDS)*	PR29B	2	RDQ29	C (LVDS)*
E25	PR16A	2	RDQS16	T (LVDS)*	PR29A	2	RDQS29	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
J22	PR15B	2	RDQ16	C	PR28B	2	RDQ29	C
H22	PR15A	2	RDQ16	T	PR28A	2	RDQ29	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C20	PT75B	1		C	PT93B	1		C
D20	PT75A	1		T	PT93A	1		T
A22	PT74B	1		C	PT92B	1		C
A21	PT74A	1		T	PT92A	1		T
GND	GNDIO1	-			GNDIO1	-		
E19	PT71B	1		C	PT85B	1		C
C19	PT71A	1		T	PT85A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
B21	PT70B	1		C	PT79B	1		C
B20	PT70A	1		T	PT79A	1		T
D19	PT69B	1		C	PT78B	1		C
B19	PT69A	1		T	PT78A	1		T
GND	GNDIO1	-			GNDIO1	-		
G17	PT68B	1		C	PT77B	1		C
E18	PT68A	1		T	PT77A	1		T
G19	PT67B	1		C	PT76B	1		C
F17	PT67A	1		T	PT76A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A20	PT66B	1		C	PT75B	1		C
A19	PT66A	1		T	PT75A	1		T
E17	PT65B	1		C	PT74B	1		C
D18	PT65A	1		T	PT74A	1		T
B18	PT64B	1		C	PT73B	1		C
GND	GNDIO1	-			GNDIO1	-		
A18	PT64A	1		T	PT73A	1		T
E16	PT63B	1		C	PT72B	1		C
G16	PT63A	1		T	PT72A	1		T
F16	PT62B	1		C	PT71B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H18	PT62A	1		T	PT71A	1		T
A17	PT61B	1		C	PT70B	1		C
B17	PT61A	1		T	PT70A	1		T
C18	PT60B	1		C	PT69B	1		C
B16	PT60A	1		T	PT69A	1		T
C17	PT59B	1		C	PT68B	1		C
GND	GNDIO1	-			GNDIO1	-		
D17	PT59A	1		T	PT68A	1		T
E15	PT58B	1		C	PT67B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
G15	PT58A	1		T	PT67A	1		T
A16	PT57B	1		C	PT66B	1		C
B15	PT57A	1		T	PT66A	1		T
D15	PT56B	1		C	PT65B	1		C
F15	PT56A	1		T	PT65A	1		T
A14	PT55B	1		C	PT64B	1		C
B14	PT55A	1		T	PT64A	1		T

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
F19	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*	
E18	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C	
GNDIO	GNDIO2	-			GNDIO2	-			
D18	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T	
VCCIO	VCCIO2	2			-	-			
F16	XRES	-			XRES	-			
C22	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12			
A21	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T	
B22	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12			
B21	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C	
C19	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12			
A18	URC_SQ_HDOUTP ₀	12		T	URC_SQ_HDOUTP ₀	12		T	
A19	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12			
B18	URC_SQ_HDOUTN ₀	12		C	URC_SQ_HDOUTN ₀	12		C	
C18	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12			
B17	URC_SQ_HDOUTN ₁	12		C	URC_SQ_HDOUTN ₁	12		C	
C17	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12			
A17	URC_SQ_HDOUTP ₁	12		T	URC_SQ_HDOUTP ₁	12		T	
C21	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12			
B20	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C	
C20	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12			
A20	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T	
B16	URC_SQ_VCCAUX ₃₃	12			URC_SQ_VCCAUX ₃₃	12			
E17	URC_SQ_REFCLK _N	12		C	URC_SQ_REFCLK _N	12		C	
D17	URC_SQ_REFCLK _P	12		T	URC_SQ_REFCLK _P	12		T	
C16	URC_SQ_VCCP	12			URC_SQ_VCCP	12			
A12	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T	
C12	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12			
B12	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C	
C11	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12			
A15	URC_SQ_HDOUTP ₂	12		T	URC_SQ_HDOUTP ₂	12		T	
C15	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12			
B15	URC_SQ_HDOUTN ₂	12		C	URC_SQ_HDOUTN ₂	12		C	
C14	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12			
B14	URC_SQ_HDOUTN ₃	12		C	URC_SQ_HDOUTN ₃	12		C	
A13	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12			
A14	URC_SQ_HDOUTP ₃	12		T	URC_SQ_HDOUTP ₃	12		T	
C13	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12			
B11	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C	
B10	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12			
A11	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T	
C10	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12			

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
F15	NC	-			NC	-			
F14	NC	-			NC	-			
F13	NC	-			NC	-			
G12	NC	-			NC	-			
G13	NC	-			NC	-			

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated sysCONFIG pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
W19	NC	-		
W18	NC	-		
V17	NC	-		
V18	NC	-		
D15	NC	-		
G14	NC	-		
G15	NC	-		
D14	NC	-		
E15	NC	-		
E14	NC	-		
F15	NC	-		
F14	NC	-		
F13	NC	-		
G12	NC	-		
G13	NC	-		
H8	VCCPLL	-		
H15	VCCPLL	-		
R8	VCCPLL	-		
R15	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA

LFE2M35E/SE					LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
C2	PL2A	7	LDQ6	T (LVDS)*	PL2A	7	LDQ6	T*	
C1	PL2B	7	LDQ6	C (LVDS)*	PL2B	7	LDQ6	C*	
F6	PL3A	7	LDQ6	T	PL3A	7	LDQ6	T	
H9	PL3B	7	LDQ6	C	PL3B	7	LDQ6	C	
D3	PL4A	7	LDQ6	T (LVDS)*	PL4A	7	LDQ6	T*	
VCCIO	VCCIO7	7			VCCIO7	7			
D2	PL4B	7	LDQ6	C (LVDS)*	PL4B	7	LDQ6	C*	
F5	PL5A	7	LDQ6	T	PL5A	7	LDQ6	T	
H8	PL5B	7	LDQ6	C	PL5B	7	LDQ6	C	
E3	PL6A	7	LDQS6	T (LVDS)*	PL6A	7	LDQS6	T*	
GNDIO	GNDIO7	-			GNDIO7	-			
E2	PL6B	7	LDQ6	C (LVDS)*	PL6B	7	LDQ6	C*	
J9	PL7A	7	LDQ6	T	PL7A	7	LDQ6	T	
E4	PL7B	7	LDQ6	C	PL7B	7	LDQ6	C	
VCCIO	VCCIO7	7			VCCIO7	7			
E1	PL8A	7	LDQ6	T (LVDS)*	PL8A	7	LDQ6	T*	
D1	PL8B	7	LDQ6	C (LVDS)*	PL8B	7	LDQ6	C*	
J8	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7/LDQ6	T	
F4	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7/LDQ6	C	
GNDIO	GNDIO7	-			GNDIO7	-			
-	-	-			VCCIO7	7			
F3	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A	T*	
F1	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A	C*	
G6	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T	PL12A	7	LUM0_SPLLT_FB_A	T	
K9	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C	PL12B	7	LUM0_SPLLC_FB_A	C	
-	-	-			GNDIO7	-			
G5	PL13A	7	LDQ15	T (LVDS)*	PL13A	7		T*	
VCCIO	VCCIO7	7			-	-			
G4	PL13B	7	LDQ15	C (LVDS)*	PL13B	7		C*	
H5	PL14A	7	LDQ15	T	PL14A	7		T	
-	-	-			VCCIO7	7			
H6	PL14B	7	LDQ15	C	PL14B	7		C	
GNDIO	GNDIO7	-			GNDIO7	-			
J7	PL16A	7	LDQ15	T	PL19A	7		T	
H4	PL16B	7	LDQ15	C	PL19B	7		C	
H3	PL17A	7	LDQ15	T (LVDS)*	PL20A	7		T*	
VCCIO	VCCIO7	7			VCCIO7	7			
G3	PL17B	7	LDQ15	C (LVDS)*	PL20B	7		C*	
GNDIO	GNDIO7	-			GNDIO7	-			
G1	PL19A	7	LDQ23	T (LVDS)*	PL23A	7	LDQ27	T*	
H1	PL19B	7	LDQ23	C (LVDS)*	PL23B	7	LDQ27	C*	
J3	PL20A	7	LDQ23	T	PL24A	7	LDQ27	T	
J4	PL20B	7	LDQ23	C	PL24B	7	LDQ27	C	
VCCIO	VCCIO7	7			VCCIO7	7			
H2	PL21A	7	LDQ23	T (LVDS)*	PL25A	7	LDQ27	T*	
J2	PL21B	7	LDQ23	C (LVDS)*	PL25B	7	LDQ27	C*	
K7	PL22A	7	LDQ23	T	PL26A	7	LDQ27	T	
J6	PL22B	7	LDQ23	C	PL26B	7	LDQ27	C	

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO2	-		
M27	PR47B	2	RDQ45	C (LVDS)*
M28	PR47A	2	RDQ45	T (LVDS)*
H30	PR46B	2	RDQ45	C
G30	PR46A	2	RDQ45	T
VCCIO	VCCIO2	2		
M25	PR45B	2	RDQ45	C (LVDS)*
M26	PR45A	2	RDQS45	T (LVDS)*
L30	PR44B	2	RDQ45	C
GNDIO	GNDIO2	-		
L29	PR44A	2	RDQ45	T
L28	PR43B	2	RDQ45	C (LVDS)*
L27	PR43A	2	RDQ45	T (LVDS)*
H29	PR42B	2	RDQ45	C
VCCIO	VCCIO2	2		
G29	PR42A	2	RDQ45	T
L22	PR41B	2	RDQ45	C (LVDS)*
M22	PR41A	2	RDQ45	T (LVDS)*
F30	PR40B	2		C
GNDIO	GNDIO2	-		
F29	PR40A	2		T
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E30	PR34B	2	RDQ32	C (LVDS)*
E29	PR34A	2	RDQ32	T (LVDS)*
-	-	-		
L25	PR33B	2	RDQ32	C
L26	PR33A	2	RDQ32	T
VCCIO	VCCIO2	2		
H28	PR32B	2	RDQ32	C (LVDS)*
J28	PR32A	2	RDQS32	T (LVDS)*
G28	PR31B	2	RDQ32	C
GNDIO	GNDIO2	-		
G27	PR31A	2	RDQ32	T
L24	PR30B	2	RDQ32	C (LVDS)*
L23	PR30A	2	RDQ32	T (LVDS)*
D30	PR29B	2	RDQ32	C
VCCIO	VCCIO2	2		
D29	PR29A	2	RDQ32	T
K24	PR28B	2	RDQ32	C (LVDS)*
K25	PR28A	2	RDQ32	T (LVDS)*
J27	PR26B	2	RDQ23	C
GNDIO	GNDIO2	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AN29	LRC_SQ_VCCRX2	13			LRC_SQ_VCCRX2	13		
AM28	LRC_SQ_HDINN2	13		C	LRC_SQ_HDINN2	13		C
AL27	LRC_SQ_VCCIB2	13			LRC_SQ_VCCIB2	13		
AM29	LRC_SQ_HDINP2	13		T	LRC_SQ_HDINP2	13		T
AL29	LRC_SQ_VCCP	13			LRC_SQ_VCCP	13		
AL30	LRC_SQ_REFCLKP	13		T	LRC_SQ_REFCLKP	13		T
AK30	LRC_SQ_REFCLKN	13		C	LRC_SQ_REFCLKN	13		C
AK29	LRC_SQ_VCCAUX33	13			LRC_SQ_VCCAUX33	13		
AM30	LRC_SQ_HDINP1	13		T	LRC_SQ_HDINP1	13		T
AL31	LRC_SQ_VCCIB1	13			LRC_SQ_VCCIB1	13		
AM31	LRC_SQ_HDINN1	13		C	LRC_SQ_HDINN1	13		C
AN30	LRC_SQ_VCCRX1	13			LRC_SQ_VCCRX1	13		
AP30	LRC_SQ_HDOUTP1	13		T	LRC_SQ_HDOUTP1	13		T
AL32	LRC_SQ_VCCOB1	13			LRC_SQ_VCCOB1	13		
AP31	LRC_SQ_HDOUTN1	13		C	LRC_SQ_HDOUTN1	13		C
AN31	LRC_SQ_VCCTX1	13			LRC_SQ_VCCTX1	13		
AP32	LRC_SQ_HDOUTN0	13		C	LRC_SQ_HDOUTN0	13		C
AM34	LRC_SQ_VCCOB0	13			LRC_SQ_VCCOB0	13		
AP33	LRC_SQ_HDOUTP0	13		T	LRC_SQ_HDOUTP0	13		T
AN32	LRC_SQ_VCCTX0	13			LRC_SQ_VCCTX0	13		
AM32	LRC_SQ_HDINN0	13		C	LRC_SQ_HDINN0	13		C
AN34	LRC_SQ_VCCIB0	13			LRC_SQ_VCCIB0	13		
AM33	LRC_SQ_HDINP0	13		T	LRC_SQ_HDINP0	13		T
AN33	LRC_SQ_VCCRX0	13			LRC_SQ_VCCRX0	13		
AH28	CFG2	8			CFG2	8		
AD24	CFG1	8			CFG1	8		
AJ29	CFG0	8			CFG0	8		
AF25	PROGRAMN	8			PROGRAMN	8		
AJ28	CCLK	8			CCLK	8		
AE25	INITN	8			INITN	8		
AK31	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AE24	WRITEN***	8			WRITEN***	8		
AJ30	CS1N***	8			CS1N***	8		
AD25	CSN***	8			CSN***	8		
AG29	D0/SPIFASTN***	8			D0/SPIFASTN***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG28	D1***	8			D1***	8		
AG30	D2***	8			D2***	8		
AH29	D3***	8			D3***	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AF26	D4***	8			D4***	8		
AH30	D5***	8			D5***	8		
AE26	D6***	8			D6***	8		
AJ31	D7/SPID0***	8			D7/SPID0***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG27	DI/CSSPI0N***	8			DI/CSSPI0N***	8		
AK32	DOUT/CSN/CSPI1N***	8			DOUT/CSN/CSPI1N***	8		
AK33	BUSY/SISPI***	8			BUSY/SISPI***	8		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35SE-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	Com	35
LFE2-35SE-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	Com	35
LFE2-35SE-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	Com	35
LFE2-35SE-5FN672C	450	1.2V	-5	Lead-Free fpBGA	672	Com	35
LFE2-35SE-6FN672C	450	1.2V	-6	Lead-Free fpBGA	672	Com	35
LFE2-35SE-7FN672C	450	1.2V	-7	Lead-Free fpBGA	672	Com	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50SE-5FN484C	339	1.2V	-5	Lead-Free fpBGA	484	Com	50
LFE2-50SE-6FN484C	339	1.2V	-6	Lead-Free fpBGA	484	Com	50
LFE2-50SE-7FN484C	339	1.2V	-7	Lead-Free fpBGA	484	Com	50
LFE2-50SE-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	Com	50
LFE2-50SE-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	Com	50
LFE2-50SE-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	Com	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70SE-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	Com	70
LFE2-70SE-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	Com	70
LFE2-70SE-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	Com	70
LFE2-70SE-5FN900C	583	1.2V	-5	Lead-Free fpBGA	900	Com	70
LFE2-70SE-6FN900C	583	1.2V	-6	Lead-Free fpBGA	900	Com	70
LFE2-70SE-7FN900C	583	1.2V	-7	Lead-Free fpBGA	900	Com	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6SE-5TN144I	90	1.2V	-5	Lead-Free TQFP	144	Ind	6
LFE2-6SE-6TN144I	90	1.2V	-6	Lead-Free TQFP	144	Ind	6
LFE2-6SE-5FN256I	190	1.2V	-5	Lead-Free fpBGA	256	Ind	6
LFE2-6SE-6FN256I	190	1.2V	-6	Lead-Free fpBGA	256	Ind	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12SE-5TN144I	93	1.2V	-5	Lead-Free TQFP	144	Ind	12
LFE2-12SE-6TN144I	93	1.2V	-6	Lead-Free TQFP	144	Ind	12
LFE2-12SE-5QN208I	131	1.2V	-5	Lead-Free PQFP	208	Ind	12
LFE2-12SE-6QN208I	131	1.2V	-6	Lead-Free PQFP	208	Ind	12
LFE2-12SE-5FN256I	193	1.2V	-5	Lead-Free fpBGA	256	Ind	12
LFE2-12SE-6FN256I	193	1.2V	-6	Lead-Free fpBGA	256	Ind	12
LFE2-12SE-5FN484I	297	1.2V	-5	Lead-Free fpBGA	484	Ind	12
LFE2-12SE-6FN484I	297	1.2V	-6	Lead-Free fpBGA	484	Ind	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5F1152C	436	1.2V	-5	fpBGA	1152	Com	70
LFE2M70SE-6F1152C	436	1.2V	-6	fpBGA	1152	Com	70
LFE2M70SE-7F1152C	436	1.2V	-7	fpBGA	1152	Com	70
LFE2M70SE-5F900C	416	1.2V	-5	fpBGA	900	Com	70
LFE2M70SE-6F900C	416	1.2V	-6	fpBGA	900	Com	70
LFE2M70SE-7F900C	416	1.2V	-7	fpBGA	900	Com	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5F1152C	520	1.2V	-5	fpBGA	1152	Com	100
LFE2M100SE-6F1152C	520	1.2V	-6	fpBGA	1152	Com	100
LFE2M100SE-7F1152C	520	1.2V	-7	fpBGA	1152	Com	100
LFE2M100SE-5F900C	416	1.2V	-5	fpBGA	900	Com	100
LFE2M100SE-6F900C	416	1.2V	-6	fpBGA	900	Com	100
LFE2M100SE-7F900C	416	1.2V	-7	fpBGA	900	Com	100